



Material Content Data Sheet



Sales Product Name		BSC097N06NS		Issued		20. July 2018		
MA#		MA001689866						
Package		PG-TDSON-8-6		Weight*		106.46 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.281	0.26	0.26	2642	2642
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		107	
	non noble metal	iron	7439-89-6	0.038	0.04		355	
	non noble metal	copper	7440-50-8	37.762	35.47	35.52	354693	355155
	noble metal	gold	7440-57-5	0.047	0.04	0.04	437	437
wire	organic material	carbon black	1333-86-4	0.088	0.08		825	
encapsulation	plastics	epoxy resin	-	6.939	6.52		65179	
	inorganic material	silicondioxide	60676-86-0	36.891	34.65	41.25	346519	412523
leadfinish	non noble metal	tin	7440-31-5	1.452	1.36	1.36	13635	13635
plating	noble metal	silver	7440-22-4	0.166	0.16	0.16	1555	1555
solder	non noble metal	tin	7440-31-5	0.009	0.01		88	
	noble metal	silver	7440-22-4	0.012	0.01		110	
heat sink CLIP	non noble metal	lead	7439-92-1	0.447	0.42	0.44	4199	4397
	inorganic material	phosphorus	7723-14-0	0.007	0.01		63	
	non noble metal	iron	7439-89-6	0.022	0.02		210	
	non noble metal	copper	7440-50-8	22.292	20.94	20.97	209383	209656
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com